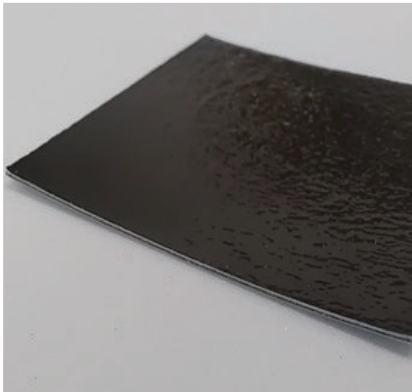
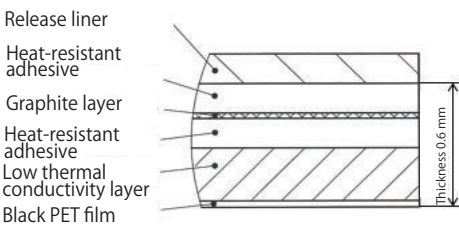




Stacked layers work together to prevent hot spots and returned heat to the device.

Features

- Ideal for attaching to the inside of plastic case of electronic devices.
- Low thermal conductivity layer reduces speed of heat transfer to graphite layer, prevents hot spots from occurring, and impedes heat reflection back to the heat source.
- One side heat-resistant adhesive tape.
- Addition of low heat reflection layer (Black PET film + Low thermal conductivity later) helps to reduce the temperature of heat source.

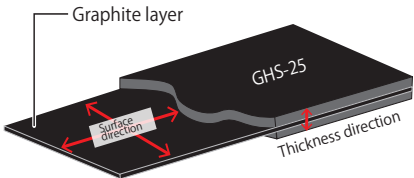


(The values are measured values, but not the product specifications or guaranteed.)

Test type	Unit	Standard	GHS-25
Thickness	mm	—	0.6
Thermal Conductivity (Thickness direction*1: whole product)	W/m·K	Hot-wire method (Company standard)	3.0 ± 1.0
Thermal Conductivity (Surface direction*1: graphite layer only)	W/m·K	Laser flash method (ASTM E1461-13)	$\geq 1,400$
Operating Temperature	°C	—	-40~150

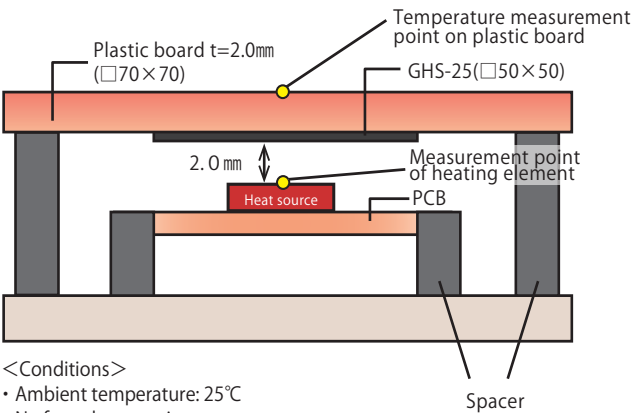
*1) Please refer to Figure1 on the right for the thermal conductivity measurement direction

Figure1: Thermal Conductivity Measurement Direction



Performance comparison

Thermal analysis model

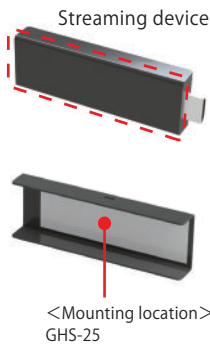


- <Conditions>
- Ambient temperature: 25°C
 - No forced convection
 - Air buoyancy considered
 - Analysis software: Femtet

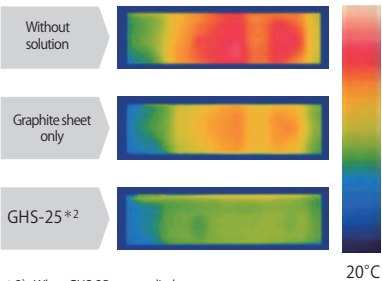
Unit: °C

	Heating element temperature	Plastic board temperature
No countermeasures	90.5	48.2
Graphite sheet only	103.7(+13.2)	39.6(-8.6)
GHS-25	83.6(-6.9)	35.9(-12.3)

Application Example



Surface temperature observation



*2) When GHS-25 was applied, CPU temperature was reduced by 3.2°C as compared to no thermal solution.